

Electronic Patent Application Fee Transmittal

Application Number:	10568755
Filing Date:	21-Feb-2006
Title of Invention:	Microsystem component and method for gluing microcomponents to a substrate
First Named Inventor/Applicant Name:	Stefan Boehm
Filer:	Michael E. Whitham/Linda Handler
Attorney Docket Number:	03100282AA

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Claims in excess of 20	1615	1	52	52
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Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Total in USD (\$)				1162